ĴΪT
 SEMI CONDUCTOR



### Features

Voltage

• Rds(on), Vgs@10V, Id@20A<5.3mΩ

40 V

- $R_{DS(ON)}$ ,  $V_{GS}@4.5V$ ,  $I_D@20A<7.4m\Omega$
- Excellent FOM
- Logic Level Drive
- AEC-Q101 qualified
- Lead free in compliance with EU RoHS 2.0
- Green molding compound as per IEC 61249 standard

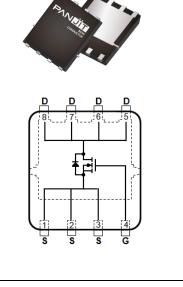
40V N-Channel Enhancement Mode MOSFET

Current

85 A

### **Mechanical Data**

- Case : DFN5060-8L Package
- Terminals : Solderable per MIL-STD-750, Method 2026
- Approx. Weight : 0.08 grams



## Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETE	SYMBOL	LIMIT	UNITS		
Drain-Source Voltage		V <sub>DS</sub>	40	V	
Gate-Source Voltage		V <sub>GS</sub>	±20		
Continuous Drain Current <sup>(Note 3)</sup>	T <sub>C</sub> =25°C		85		
	Tc=100°C	I <sub>D</sub>	60	А	
Pulsed Drain Current <sup>(Note 1)</sup>	T <sub>C</sub> =25°C	I <sub>DM</sub>	340		
Power Dissipation	T <sub>C</sub> =25°C	D-	68	14/	
	Tc=100°C	PD -	34	W	
Continuous Drain Current <sup>(Note 4)</sup>	T <sub>A</sub> =25°C		18.7	Δ	
	T <sub>A</sub> =70°C	I <sub>D</sub>	15.6	A	
Power Dissipation	T <sub>A</sub> =25°C	Da	3.3	- W	
	T <sub>A</sub> =70°C	PD	2.3		
Single Pulse Avalanche Energy <sup>(Note 5)</sup>		Eas	90	mJ	
Operating Junction and Storage Temperature Range		Tj,Tstg	-55~175	°C	
Thermal Resistance <sup>(Note 4)</sup>	Junction to Case	$R_{\theta JC}$	2.2	°C/W	
	Junction to Ambient	R <sub>θJA</sub>	45		



## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static	·	-				
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40	-	-	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =50uA	1.1	1.7	2.3	V
Drain-Source On-State Resistance		V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	4.2	5.3	mΩ
	R <sub>DS(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	5.7	7.4	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ =40V, $V_{GS}$ =0V	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Dynamic <sup>(Note 6)</sup>	-	-		•		
Total Gate Charge	Qg		-	20	-	
Gate-Source Charge	Qgs	V <sub>DS</sub> =32V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V	-	3.1	-	nC
Gate-Drain Charge	$Q_{gd}$		-	6.4	-	
Input Capacitance	Ciss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	-	1320	-	pF
Output Capacitance	Coss		-	250	-	
Reverse Transfer Capacitance	Crss		-	30	-	
Gate resistance	Rg	f=1MHz	-	0.8	-	Ω
Turn-On Delay Time	td(on)		-	8	-	
Turn-On Rise Time	tr	V <sub>DS</sub> =32V, I <sub>D</sub> =20A, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω (Note 2)	-	36	-	
Turn-Off Delay Time	td(off)		-	19	-	ns
Turn-Off Fall Time	tf		-	55	-	
Drain-Source Diode	•		·			
Diode Forward Current	I <sub>S</sub>	T 0-°0	-	-	85	
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>c</sub> =25°C	-	-	340	A
Diode Forward Voltage	V <sub>SD</sub>	Is=20A, V <sub>GS</sub> =0V	-	0.85	1.3	V
Reverse Recovery Time	Trr	V <sub>GS</sub> =0V, I <sub>S</sub> =20A	-	43	-	ns
Reverse Recovery Charge	Qrr	dls/dt=100A/us	-	34	-	nC

NOTES :

- 1. Pulse width100us, Duty cycle<2%.</td>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. Chip capability with an  $R_{\theta JC}=2.2^{\circ}C/W$ .
- 4.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. Mounted on a 1 inch<sup>2</sup> with 2oz.square pad of copper.
- 5. The test condition is L=0.5mH, I\_{AS}=19A, V\_{DD}=25V, V\_{GS}=10V, Starting T\_J=25^{\circ}C.
- 6. Guaranteed by design, not subject to production testing.

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0 0 1 2 3 4 5 2 5 6 3 4 V<sub>GS</sub>-Gate-to-Source Voltage (V) V<sub>DS</sub>-Drain-to-Source Voltage (V) **Fig.1 On-Region Characteristics Fig.2 Transfer Characteristics** 10 1.8 Ros(on)-On-Resistance(Normalized) g 1.6 V<sub>GS</sub>=10V, I<sub>D</sub>=20A 8 V<sub>GS</sub>=4.5V Ros(on)-On-Resistance 1.4 6 1.2 4 V<sub>GS</sub>=4.5V, I<sub>D</sub>=20A V<sub>GS</sub>=10∀ 1.0 2 0.8 0 0.6 0 17 34 51 68 85 -25 25 75 125 -75 175 Temperature (°C) IDS-Drain-to-Source Current (A) Fig.3 On-Resistance vs. Drain Current Fig.4 On-Resistance vs. Junction temperature 1000 20 I<sub>D</sub>=20A Isp-Source-to-Drain Current (A) R<sub>bs(on)</sub>-On-Resistance (mΩ) 15 100 T\_=125℃ T₁=25°C 10 10 T\_\_=-40°C T₁=25°C T\_=125°C 1 5 TJ=-40℃ 0.1 0 0.4 0 0.2 0.6 0.8 1.2 1.4 1 0 2 4 6 8 10 V<sub>GS</sub>-Gate-to-Source Voltage (V) V<sub>SD</sub>-Source-to-Drain Voltage (V) Fig.5 On-Resistance Variation with V<sub>GS</sub> Fig.6 Source-Drain Diode Forward Voltage

200

160

120

80

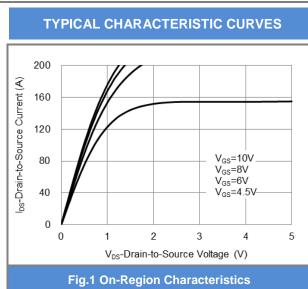
40

I<sub>DS</sub>-Drain-to-Source Current (A)

V<sub>DS</sub>=3V

T<sub>J</sub>=125°C

TJ=-40℃





**PJQ5546-AU** 

T₁=25°C

January 30,2023

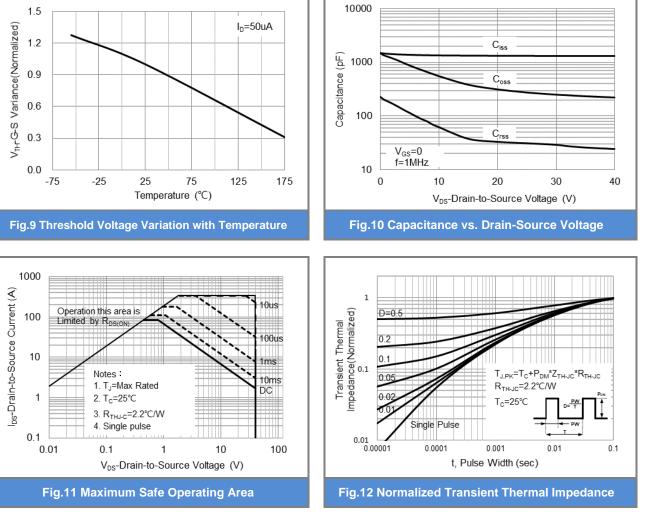
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125

Fig.8 Breakdown Voltage Variation vs. Temperature

175



**TYPICAL CHARACTERISTIC CURVES** 

### PANJ SEM CONDUCTOR

10

8

6

4

2

0 0

V<sub>GS</sub>-Gate-to-Source Voltage (V)



V<sub>DS</sub>=32V

5

I<sub>D</sub>=20A

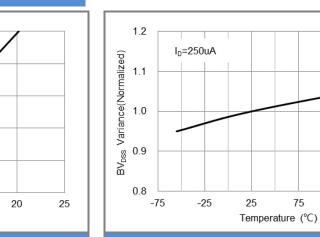
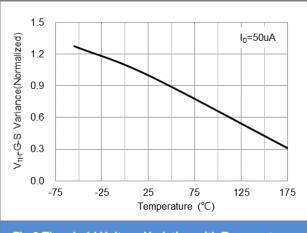


Fig.7 Gate-Charge Characteristics

Qg (nC)

15

10

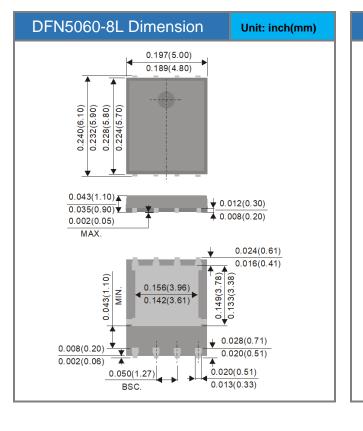


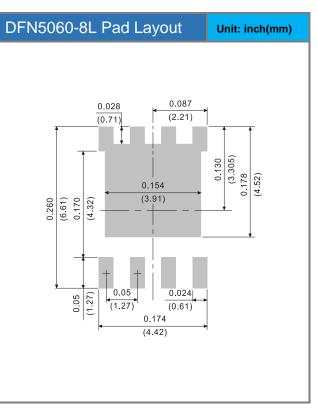


## Part No. Packing Code Version

Part No. Packing Code	Package Type	Packing Type	Marking	Version
PJQ5546-AU_R2_002A1	DFN5060-8L	3K pcs / 13" reel	Q5546	Halogen free RoHS compliant

## Packaging Information & Mounting Pad Layout







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